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SPECIFICATION

VXT350QHI-26C

☐ Preliminary Specification

☐ Final Specification



CUSTOMER:

Made By:

Checked By:

Approved By:

Quality:

Date:

Note:

Approved By:

Date:

Note:

2. Revision Record

Date	Rev.No.	Page	Revision Items	Prepared
2020-06-16	V0		The first release	RCR

3. General Specifications

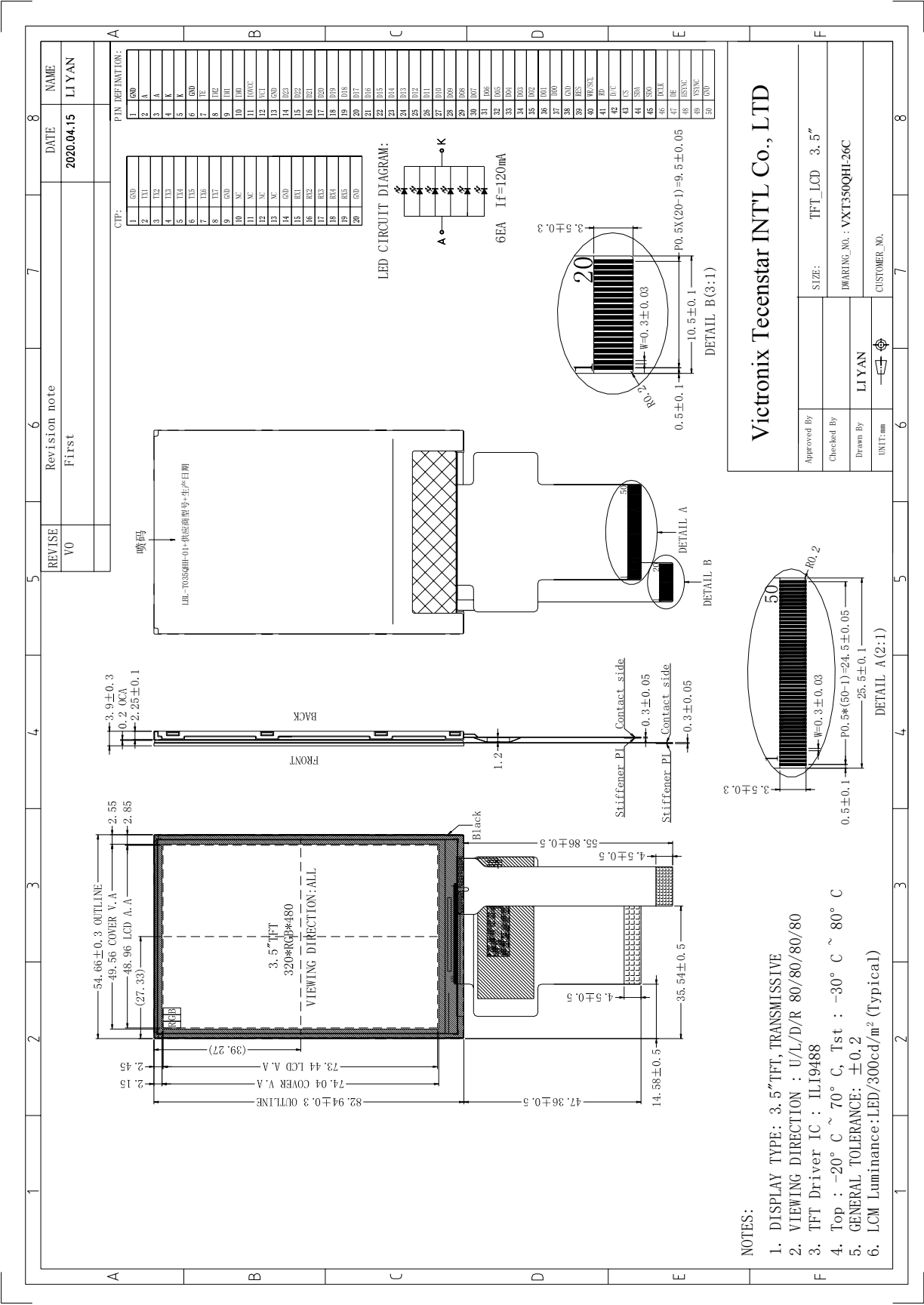
VXT350QHI-26C is a TFT-LCD module. It is composed of a TFT-LCD panel, driver IC, FPC, a back light and CTP unit . The 3.5'' display area contains 320 x(RGB)x480 pixels and can display up to 16.7M colors. This product accords with ROHS environmental criterion.

Item	Contents	Unit	Note
LCD Type	TFT	-	
Display color	16.7M		1
Viewing Direction	ALL	O'Clock	
Operating temperature	-20~+70	℃	
Storage temperature	-30~+80	℃	
Module size	54.66X82.94X3.90	mm	2
Active Area(W×H)	48.96X73.44	mm	
Number of Dots	320 x480	dots	
TFT Controller	ILI9488	-	
CTP Driver	-	-	
Power Supply Voltage	2.8	V	
Backlight	6P-LEDs (white)	pcs	
Weight	---	g	
Interface	MCU/RGB/SPI	-	

Note 1: Color tune is slightly changed by temperature and driving voltage.

Note 2: Without FPC and Solder.With CTP.

4.Outline Drawing



5. Absolute Maximum Ratings($T_a=25^{\circ}\text{C}$)

5.1 Electrical Absolute Maximum Ratings.($V_{ss}=0\text{V}$, $T_a=25^{\circ}\text{C}$)

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	V _{CI}	-0.3	3.3	V	1, 2
	IOVCC	-0.3	3.3	V	1, 2

Notes:

- If the module is above these absolute maximum ratings. It may become permanently damaged.
Using the module within the following electrical characteristic conditions are also exceeded, the module will malfunction and cause poor reliability.
- $V_{CI} > V_{SS}$ must be maintained.

5.2 Environmental Absolute Maximum Ratings.

Item	Storage		Operating		Note
	MIN.	MAX.	MIN.	MAX.	
Ambient Temperature	-30°C	80°C	-20°C	70°C	1,2
Humidity	-	-	-	-	3

Notes:

- The response time will become lower when operated at low temperature.
- Background color changes slightly depending on ambient temperature.
The phenomenon is reversible.
- $T_a \leq 40^{\circ}\text{C}$:85%RH MAX.
 $T_a > 40^{\circ}\text{C}$:Absolute humidity must be lower than the humidity of 85%RH at 40°C .

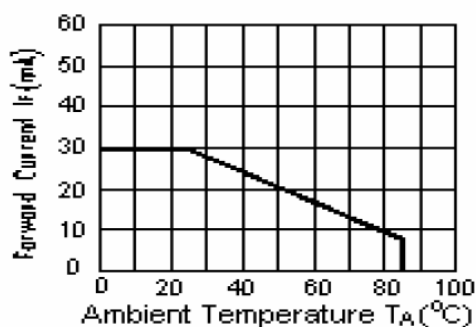
6. Electrical Specifications

6.1 Electrical characteristics($V_{SS}=0V$, $T_a=25^{\circ}C$)

Parameter	Symbol	Condition	Min	Typ	Max	Unit	Note
Power supply	VCI	$T_a=25^{\circ}C$	2.5	2.8	3.3	V	
	IOVCC	$T_a=25^{\circ}C$	1.65	1.8	3.3	V	
Input voltage	'H'	V_{IH}	$T_a=25^{\circ}C$	0.7IOVCC	-	IOVCC	V
	'L'	V_{IL}	$T_a=25^{\circ}C$	-0.3	-	0.3IOVCC	V

6.2 LED backlight specification($V_{SS}=0V$, $T_a=25^{\circ}C$)

Item	Symbol	Condition	Min	Typ	Max	Unit	Note
Supply voltage	V_f	$I_f=120mA$	2.7	3.0	3.3	V	
Uniformity	ΔB_p	$I_f=120mA$	75	80	-	%	
Life Time	time	$I_f=120mA$	-	20K	-	hours	1



Note 1: Brightness to be decreased to 50% of the initial value at ambient temperature $T_A=25^{\circ}C$

6.3 Interface signals

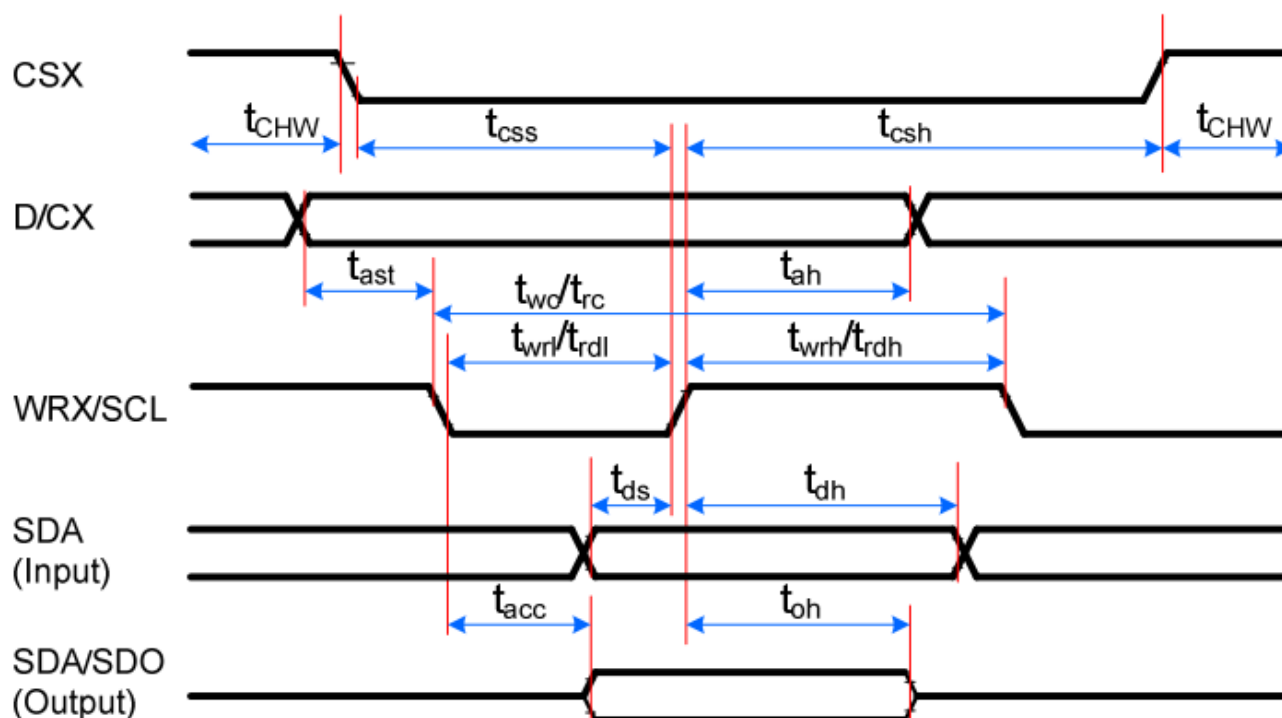
Pin No.	Symbol	I/O	Function																																				
1	GND	P	Ground.																																				
2~3	A	P	LED back light(Anode)																																				
4~5	K	P	LED back light(Cathode)																																				
6	GND	P	Ground.																																				
7	TE	O	Serve as a TE(Tearing effect) output signal																																				
8	IM2	I	Select the interface mode <table><thead><tr><th>IM2</th><th>IM1</th><th>IM0</th><th>Interface</th></tr></thead><tbody><tr><td>0</td><td>0</td><td>0</td><td>MIPI-DBI Type B 24-bit bus (DB_EN = 1)</td></tr><tr><td>0</td><td>0</td><td>0</td><td>MIPI-DBI Type B 18-bit bus (DB_EN = 0)</td></tr><tr><td>0</td><td>0</td><td>1</td><td>MIPI-DBI Type B 9-bit bus</td></tr><tr><td>0</td><td>1</td><td>0</td><td>MIPI-DBI Type B 16-bit bus</td></tr><tr><td>0</td><td>1</td><td>1</td><td>MIPI-DBI Type B 8-bit bus</td></tr><tr><td>1</td><td>0</td><td>1</td><td>MIPI-DBI Type C Option 1 (3-line SPI)</td></tr><tr><td>1</td><td>1</td><td>0</td><td>MIPI DSI</td></tr><tr><td>1</td><td>1</td><td>1</td><td>MIPI-DBI Type C Option 3 (4-line SPI)</td></tr></tbody></table>	IM2	IM1	IM0	Interface	0	0	0	MIPI-DBI Type B 24-bit bus (DB_EN = 1)	0	0	0	MIPI-DBI Type B 18-bit bus (DB_EN = 0)	0	0	1	MIPI-DBI Type B 9-bit bus	0	1	0	MIPI-DBI Type B 16-bit bus	0	1	1	MIPI-DBI Type B 8-bit bus	1	0	1	MIPI-DBI Type C Option 1 (3-line SPI)	1	1	0	MIPI DSI	1	1	1	MIPI-DBI Type C Option 3 (4-line SPI)
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9	IM1	I																																					
10	IM0	I																																					
11	IOVCC	P	Digital IO Pad power supply(1.8V&2.8V)																																				
12	VCI	P	Power supply (2.8V)																																				
13	GND	P	Ground.																																				
14-37	D23-D00	I	Data pin.Fix to DGND level when not in use.																																				
38	GND	P	Ground.																																				
39	RES	I	Reset signal,Signal is active low.																																				
40	WR/SCL	I	DBI Type B: WRX pin, serves as a write signal . DBI Type C: SCL pin as Serial Clock when operates in the serial interface. Fix to IOVCC level when not in use.																																				
41	RD	I	DBI Type B: serve as a read signal .Fix to IOVCC level when not in use.																																				
42	D/C	I	DBI Type B: Data/Command Selection pin.Fix to IOVCC level when not in use.																																				
43	CS	I	DBI Type B:Chip select signal.Fix to IOVCC level when not in use.																																				
44	SDA	I	DBI Type C:Serial Input data bus.Fix to GND level when not in use.																																				
45	SDO	I	DBI Type C:Serial output data bus.Fix to GND level when not in use.																																				
46	DCLK	I	Data clock.Fix to GND level when not in use.																																				
47	DE	I	Data enable pin.Fix to GND level when not in use.																																				
48	HSYNC	I	Line sync signal.Fix to GND level when not in use.																																				
49	VSYNC	I	Frame sync signal.Fix to GND level when not in use.																																				
50	GND	P	Ground.																																				

CTP PIN:

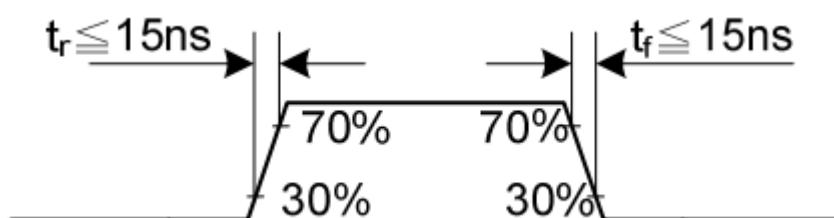
Pin No.	Symbol	I/O	Function
1	GND	P	Ground
2-8	TX1-7	I	data bus
9	GND	P	Ground
10-13	NC	-	No connection
14	GND	P	Ground
15-19	RX1-5	I	data bus
20	GND	P	Ground

6.4 AC Characteristics

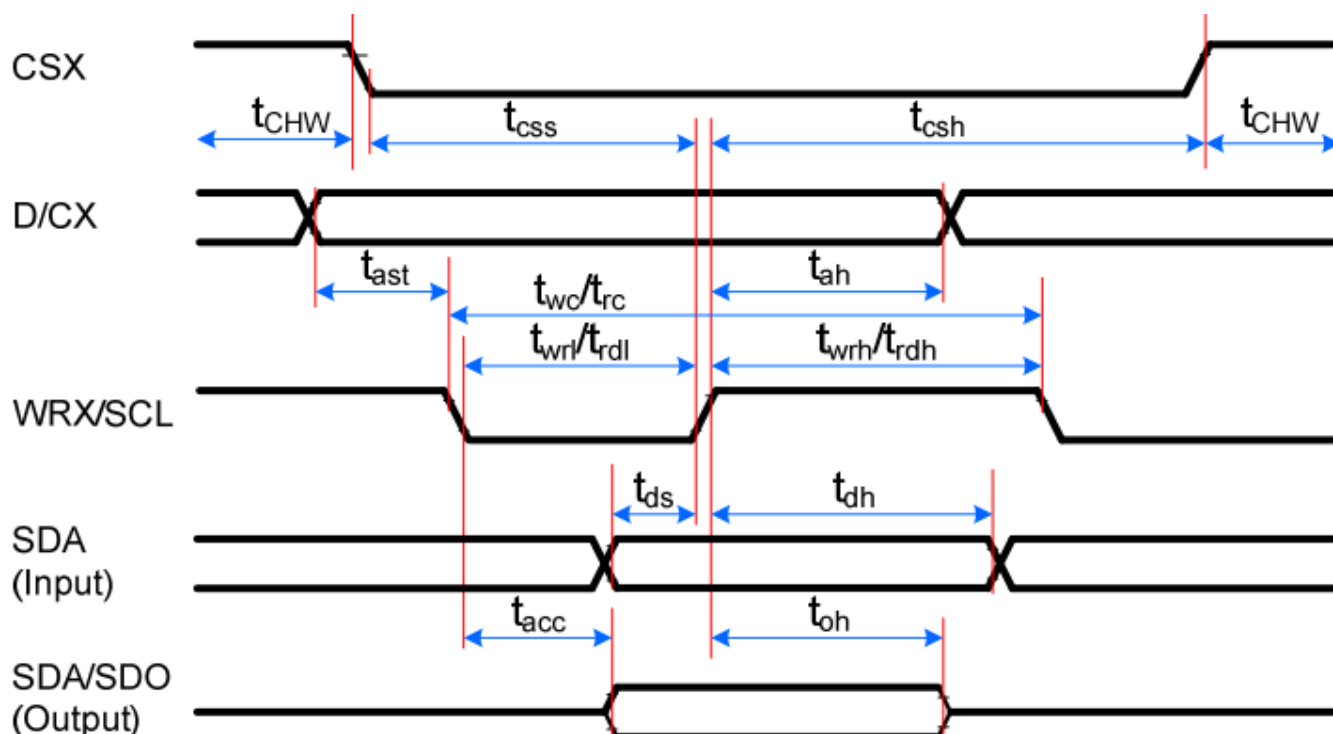
Display Serial Interface Timing Characteristics (3-line SPI system)



Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC/ HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	16-/18-/24-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
ENABLE	t_{ENS}	ENABLE setup time	15	-	ns	
	t_{ENH}	ENABLE hold time	15	-	ns	
DB [23:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level period	20	-	ns	
	PWDL	DOTCLK low-level period	20	-	ns	
	t_{CYCD}	DOTCLK cycle time	50	-	ns	
	$t_{\text{rgbr}}, t_{\text{rgbl}}$	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

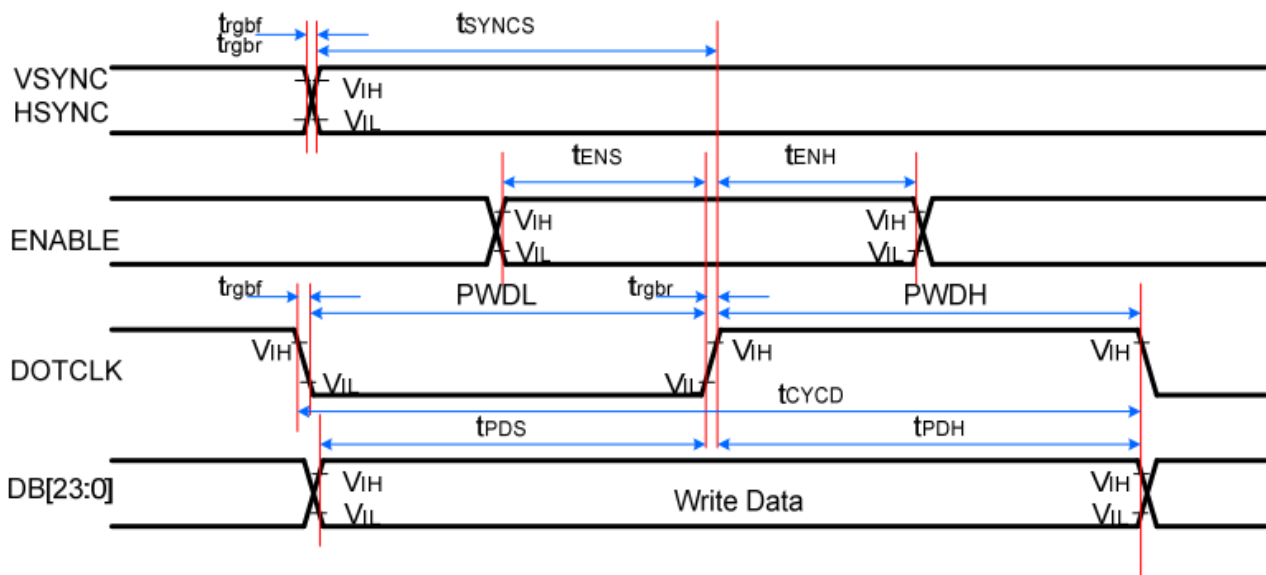


Display Serial Interface Timing Characteristics (4-line SPI system)

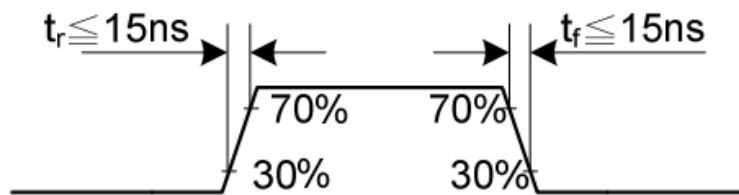


Signal	Symbol	Parameter	min	max	Unit	Description
CSX	tcss	Chip select time (Write)	15	-	ns	
	tcsh	Chip select hold time (Read)	15	-	ns	
	tCHW	CS H pulse width	40	-	ns	
SCL	twc	Serial clock cycle (Write)	50	-	ns	
	twrh	SCL H pulse width (Write)	10	-	ns	
	twrl	SCL L pulse width (Write)	10	-	ns	
	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL H pulse width (Read)	60	-	ns	
	trdl	SCL L pulse width (Read)	60	-	ns	
D/CX	tas	D/CX setup time	10	-	ns	
	tah	D/CX hold time (Write/Read)	10	-	ns	
SDA (Input)	tds	Data setup time (Write)	10	-	ns	
	tdh	Data hold time (Write)	10	-	ns	
SDA/SDO (Output)	tacc	Access time (Read)	10	50	ns	For maximum CL=30pF
	tod	Output disable time (Read)	15	50	ns	For minimum CL=8pF

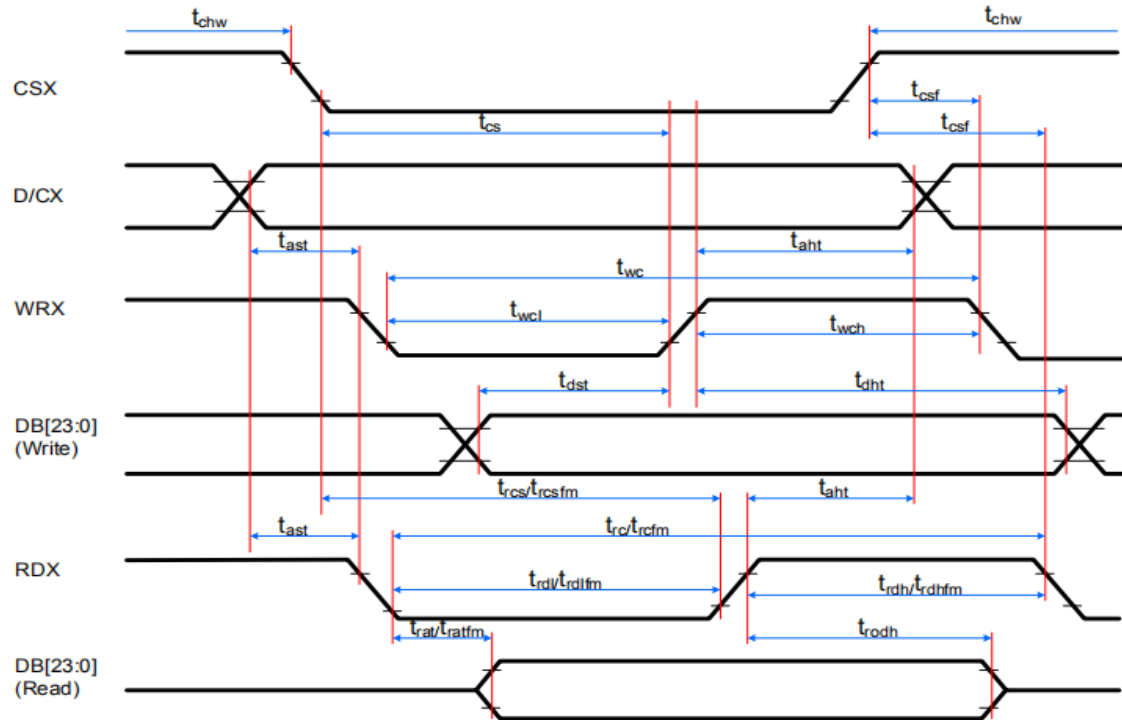
Parallel 24/18/16-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC/HSYNC	tSYNCS	VSYNC/HSYNC setup time	15	-	ns	16-/18-/24-bit bus RGB interface mode
	tSYNCH	VSYNC/HSYNC hold time	15	-	ns	
ENABLE	tENS	ENABLE setup time	15	-	ns	
	tENH	ENABLE hold time	15	-	ns	
DB [23:0]	tPOS	Data setup time	15	-	ns	
	tPDH	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level period	20	-	ns	
	PWDL	DOTCLK low-level period	20	-	ns	
	tCYCD	DOTCLK cycle time	50	-	ns	
	tgrbr, tgrbf	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

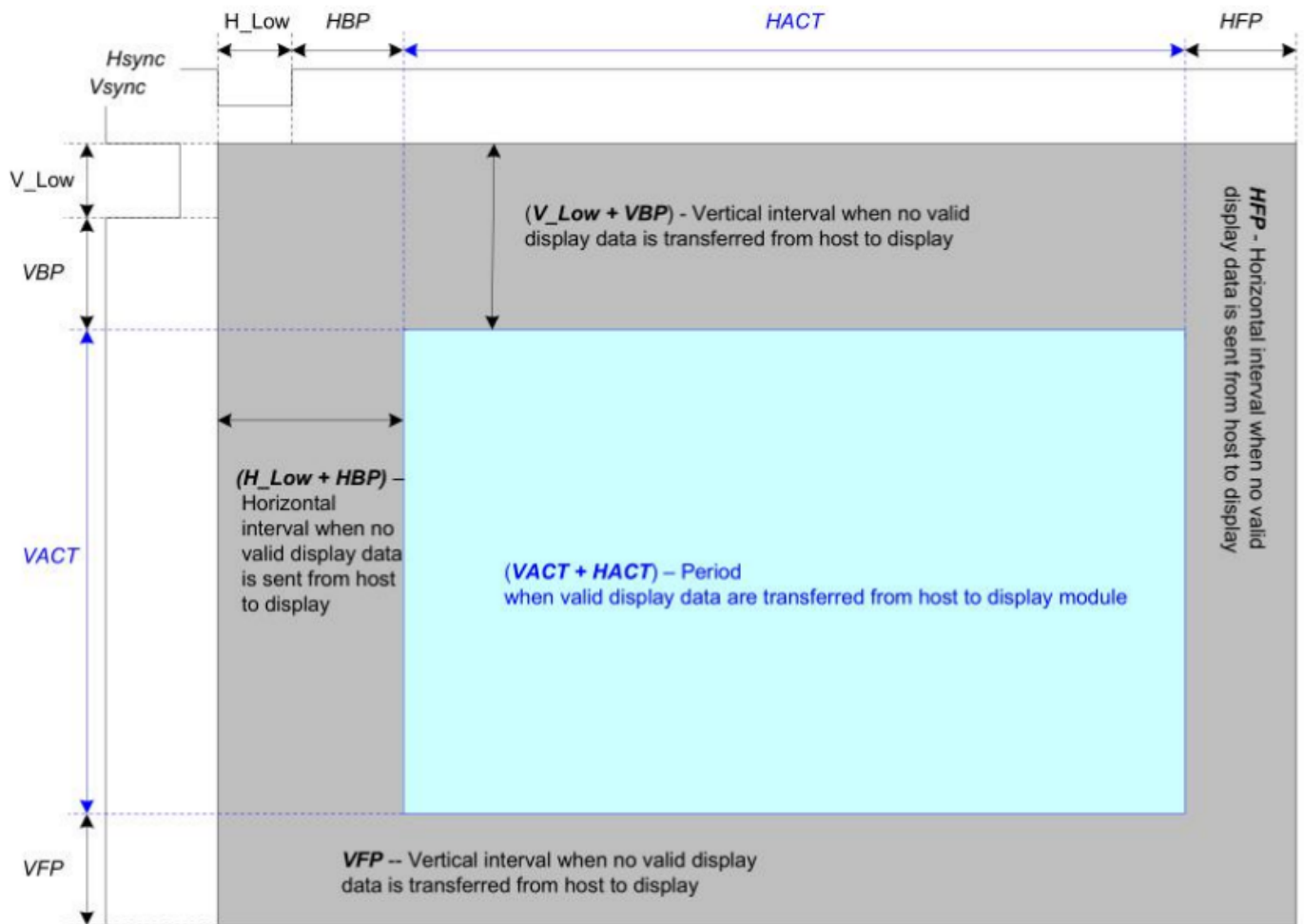


MCU Interface Timing Characteristics



Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	-
	that	Address hold time (Write/Read)	0	-	ns	-
CSX	tchwh	CSX "H" pulse width	0	-	ns	-
	tcs	Chip Select setup time (Write)	15	-	ns	-
	trcs	Chip Select setup time (Read ID)	45	-	ns	-
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	-
	tcsf	Chip Select Wait time (Write/Read)	0	-	ns	-
WRX	twc	Write cycle	40	-	ns	-
	twrh	Write Control pulse H duration	15	-	ns	-
	twrl	Write Control pulse L duration	15	-	ns	-
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	When read from Frame Memory
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	When read ID data
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
DB [23:0], DB [17:0], DB [15:0], DB [8:0], DB [7:0]	tdst	Write data setup time	10	-	ns	For maximum, CL=30pF For minimum, CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

6.5 General Timing Diagram



Parameters	Symbols	Min.	Typ.	Max.	Units
Horizontal Synchronization	H_Low	3	-	H_Low+HBP <192	DOTCLK
Horizontal Back Porch	HBP	3	-		DOTCLK
Horizontal Front Porch	HFP	3	-	255	DOTCLK
Horizontal Address	HACT	-	320	-	DOTCLK
Horizontal Frequency		-	-	33	KHz
Vertical Synchronization	V_Low	1	-	V_Low+VBP+VFP < 32	Line
Vertical Back Porch	VBP	2	-		Line
Vertical Front Porch	VFP	2	-		Line
Vertical Address	VACT	-	480	-	Line
Vertical Frequency		60	-	70	Hz
DOTCLK cycle		100	-	50	ns
DOTCLK Frequency		10	-	20	MHz

Example : DOTCLK = 20Mhz, TE=70Hz, V_Low+VBP=2, VFP=2, H_Low+HBP=100, HFP=170.

7. Optical Characteristics

Item	Symbol		Condition	Min.	Typ.	Max.	Unit	Note
Brightness	Bp		$\theta=0^{\circ}$ $\Phi=0^{\circ}$	-	300	-	Cd/m ²	1
Uniformity	$\angle$ Bp			75	80	-	%	1,2
Viewing Angle	3:00		Cr≥10	-	80	-	Deg	3
	6:00			-	80	-		
	9:00			-	80	-		
	12:00			-	80	-		
Contrast Ratio	Cr		$\theta=0^{\circ}$ $\Phi=0^{\circ}$	-	700	-	-	4
Response Time	T _r +T _f			-	30	-	ms	5
Color of CIE Coordinate	W	x	$\theta=0^{\circ}$ $\Phi=0^{\circ}$	Typ. -0.05	0.315	Typ. +0.05	-	1,6
		y			0.370		-	
	R	x			0.660		-	
		y			0.325		-	
	G	x			0.277		-	
		y			0.568		-	
	B	x			0.145		-	
		y			0.072		-	
NTSC Ratio	S		-	69	-	%		

Note: The parameter is slightly changed by temperature, driving voltage and materiel

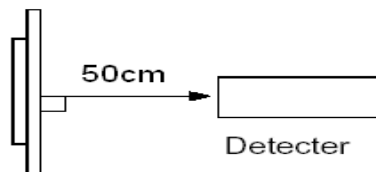
Note 1: The data are measured after LEDs are turned on for 5 minutes. LCM displays full white.

The brightness is the average value of 9 measured spots. Measurement equipment BM-7 (Φ5mm)

Measuring condition:

- *Measuring surroundings: Dark room.*
- *Measuring temperature: $T_a=25^{\circ}\text{C}$.*
- *Adjust operating voltage to get optimum contrast at the center of the display.*

Measured value at the center point of LCD panel after more than 5 minutes while backlight turning on.

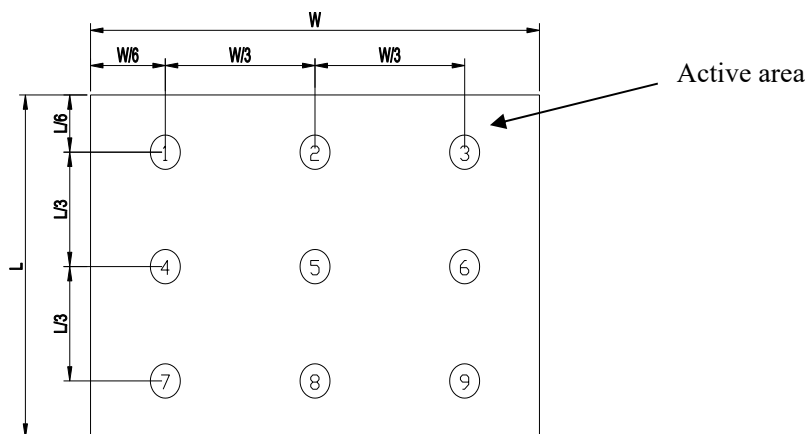


Note 2: The luminance uniformity is calculated by using following formula.

$$\Delta Bp = Bp (\text{Min.}) / Bp (\text{Max.}) \times 100 (\%)$$

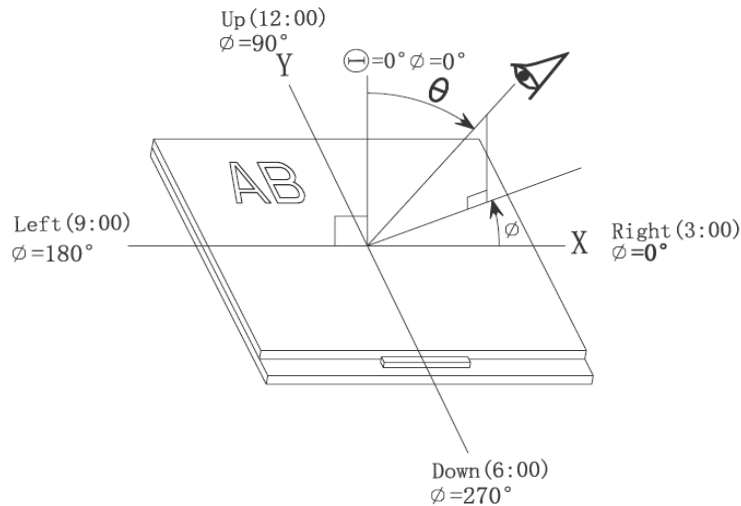
$Bp (\text{Max.})$ = Maximum brightness in 9 measured spots

$Bp (\text{Min.})$ = Minimum brightness in 9 measured spots.

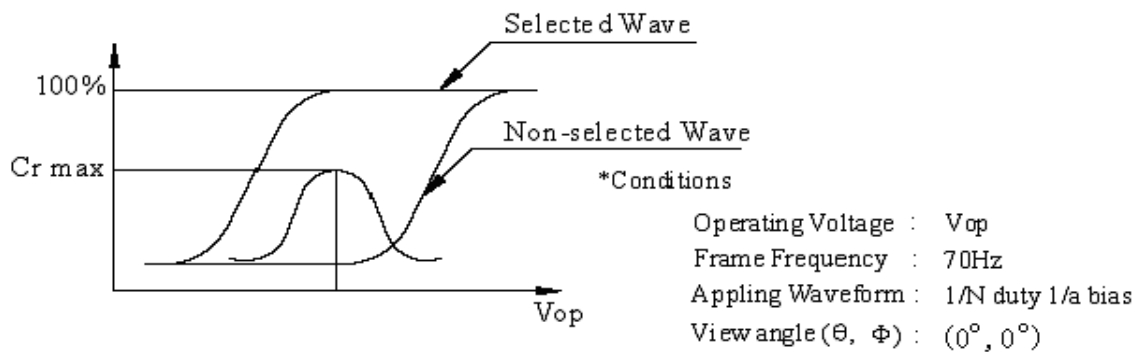


Note 3: The definition of viewing angle:

Refer to the graph below marked by θ and Φ



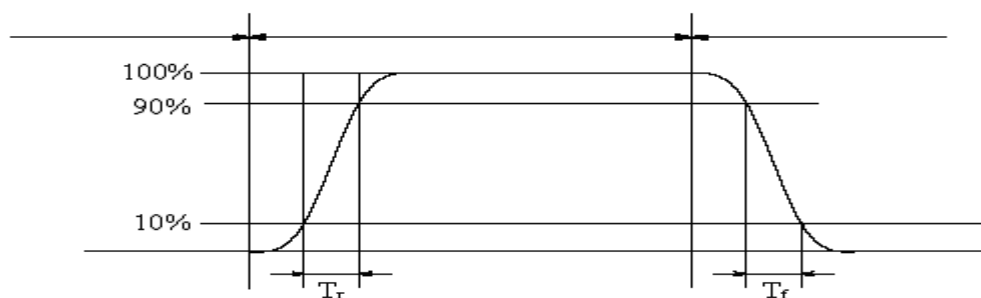
Note 4: Definition of contrast ratio.(Test LCD using DMS501)



$$\text{Contrast ratio}(Cr) = \frac{\text{Brightness of selected dots}}{\text{Brightness of non-selected dots}}$$

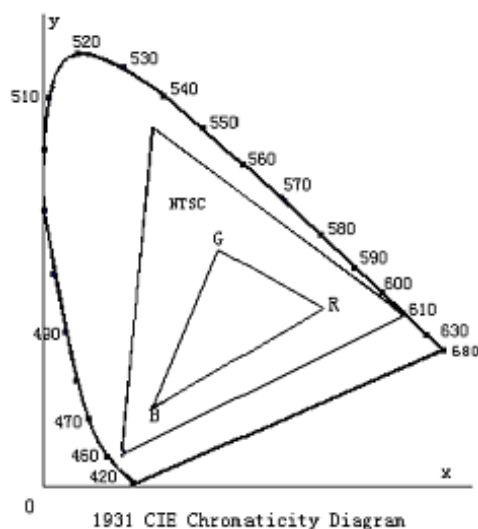
Note 5: Definition of Response time. (Test LCD using DMS501):

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of amplitudes. Refer to figure as below.



The definition of response time

Note 6: Definition of Color of CIE Coordinate and NTSC Ratio.

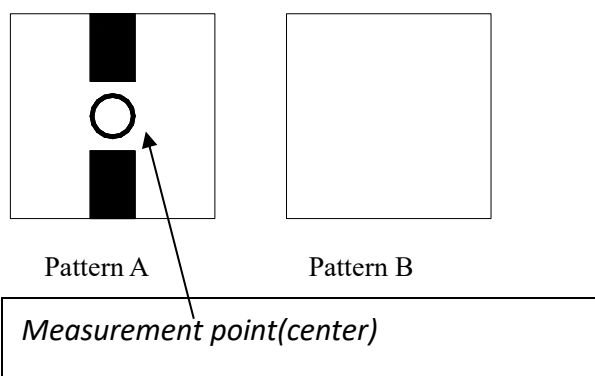


Color gamut:

$$S = \frac{\text{area of RGB triangle}}{\text{area of NTSC triangle}} \times 100\%$$

Note 7: Definition of cross talk.

Cross talk ratio(%)=|pattern A Brightness-pattern B Brightness|/pattern A Brightness*100



Electric volume value=3F+/-3Hex

8. Reliability Test Items and Criteria

Test Item	Test condition	Remark
High Temperature Storage	Ta = 80℃ 96hrs	Note1,Note3, 4
Low Temperature Storage	Ta = -30℃ 96hrs	Note1,Note3, 4
High Temperature Operation	Ta = 70℃ 96hrs	Note2,Note3, 4
Low Temperature Operation	Ta = -20℃ 96hrs	Note1,Note3, 4
Operation at High Temperature/Humidity	+60℃, 90%RH 96hrs	Note3, 4
Thermal Shock	-30℃/30 min ~ +80℃/30 min for a total 10 cycles, Start with cold temperature and end with high temperature.	Note3, 4
Vibration Test	Frequency range:10~55Hz Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X. Y. Z. (6 hours for total)	
Mechanical Shock	100G 6ms,±X, ±Y, ±Z 3 times for each direction	
Package Vibration Test	Random Vibration : 0.015G*G/Hz from 5-200HZ, -6dB/Octave from 200-500HZ 2 hours for each direction of X. Y. Z. (6 hours for total)	
Package Drop Test	Height:60cm 1 corner, 3 edges, 6 surfaces	
Electro Static Discharge	±2KV, Human Body Mode, 100pF/1500Ω	

Note 1: Ta is the ambient temperature of samples.

Note 2: Ts is the temperature of panel's surface.

Note 3: In the standard condition, there shall be no practical problem that may affect the display function. After the reliability test, the product only guarantees operation, but don't guarantee all of the cosmetic specification.

Note 4: Before cosmetic and function test, the product must have enough recovery time,at least 2 hours at room temperature

9. Precautions for Use of LCD Modules

9.1 Handling Precautions

9.1.1 *The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.*

9.1.2 *If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.*

9.1.3 *Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.*

9.1.4 *The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.*

9.1.5 *If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:*

— Isopropyl alcohol — Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

— Water — Ketone — Aromatic solvents

9.1.6 *Do not attempt to disassemble the LCD Module.*

9.1.7 *If the logic circuit power is off, do not apply the input signals.*

9.1.8 *To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.*

a. Be sure to ground the body when handling the LCD Modules.

b. Tools required for assembly, such as soldering irons, must be properly ground.

c. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.

d. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

9.2 Storage precautions

9.2.1 *When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.*

9.2.2 *The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:*

Temperature : $0^{\circ}\text{C} \sim 40^{\circ}\text{C}$

Relatively humidity: $\leq 80\%$

9.2.3 *The LCD modules should be stored in the room without acid, alkali and harmful gas.*

9.3 *The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.*

END